



## SILICON PLANAR ZENER DIODES

BZV55BXXX BZV55CXXX

LL-34
Glass Case MiniMELF
RoHS compliant



LL-34 (Mini MELF)

### **GENERAL DESCRIPTION:**

MiniMELF package is specially for automatic insertion, The zener voltages are graded according to international E24 standard

#### **FEATURES:**

- 1. Total power dissipation: max. 500 mW
- 2. Two tolerance series: B ± 2% and approx. C ± 5%
- 3. This product is available in AEC-Q101 Compliant and PPAP Capable also.

Note: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering.

**APPLICATIONS:** Low voltage stabilizers or voltage references

## ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	VALUE	UNIT
Power Dissipation	P <sub>tot</sub>	500 <sup>1</sup>	mW
Junction and Storage Temperature Range	$T_J,T_stg$	-65 to +200	°C

## ELECTRICAL CHARACTERISTICS at T<sub>a</sub> = 25 °C

Parameter	Symbol	VALUE	Unit
Thermal Resistance Junction to Ambient Air	RthA	0.3 1	K/mW
Forward Voltage at I <sub>F</sub> = 10 mA	$V_{F}$	1	V

#### Note:

1. Valid provided that electrodes are kept at ambient temperature.







**ELECTRICAL CHARACTERISTICS at** (Ta = 25 °C Unless otherwise specified)

		age Range <sup>2</sup>	Dynamic Resistance		Reverse Leakage Current			Temp.		
BZV55B or	V <sub>zT</sub>		I <sub>ZT</sub>	Z <sub>zT</sub> at	<b>Z</b> <sub>ZK</sub>	at I <sub>zk</sub>	I <sub>R</sub> @ Ta=25°C	I <sub>R</sub> @ Ta=125°C	at V <sub>R</sub>	Coefficient of Zener Voltage
BZV55C	BZV55B (Tol. ± 2%)	BZV55C (Tol. ± 5%)	(mA)	Max. (Ω)	Max. (Ω)	mA	Max. (µA)	Max. (μA)	(V)	TK <sub>vz</sub> (%/K)
2V4	2.352.45	2.22.6	5	100	600	1	50	100	1	-0.09~-0.06
2V7	2.652.75	2.52.9	5	100	600	1	20	50	1	-0.08~-0.05
3V0	2.943.06	2.83.2	5	95	600	1	10	40	1	-0.08~-0.05
3V3	3.233.37	3.13.5	5	95	600	1	5	40	1	-0.08~-0.05
3V6	3.533.67	3.43.8	5	90	600	1	5	40	1	-0.08~-0.05
3V9	3.823.98	3.74.1	5	90	600	1	3	40	1	-0.08~-0.05
4V3	4.214.39	44.6	5	90	600	1	3	20	1	-0.06~-0.03
4V7	4.614.79	4.45	5	80	600	1	3	10	1	-0.05~+0.02
5V1	55.2	4.85.5	5	60	550	1	2	2	1	-0.02~+0.02
5V6	5.495.71	5.26	5	40	450	1	1	2	1	-0.05~+0.05
6V2	6.086.32	5.86.6	5	10	200	1	3	2	2	0.03~0.06
6V8	6.666.94	6.47.2	5	15	150	1	2	2	3	0.03~0.07
7V5	7.357.65	77.9	5	15	80	1	1	2	5	0.03~0.07
8V2	8.048.36	7.78.7	5	15	80	1	0.7	2	6.2	0.03~0.08
9V1	8.929.28	8.59.6	5	15	100	1	0.5	2	6.8	0.03~0.09
10	9.810.2	9.410.6	5	20	150	1	0.2	2	7.5	0.03~0.10
11	10.811.2	10.411.6	5	20	150	1	0.1	2	8.2	0.03~0.11
12	11.812.2	11.412.7	5	25	150	1	0.1	2	9.1	0.03~0.11
13	12.713.3	12.414.1	5	30	170	1	0.1	2	10	0.03~0.11
15	14.715.3	13.815.6	5	30	200	1	0.1	2	11	0.03~0.11
16	15.716.3	15.317.1	5	40	200	1	0.1	2	12	0.03~0.11
18	17.618.4	16.819.1	5	45	225	1	0.1	2	13	0.03~0.11
20	19.620.4	18.821.2	5	55	225	1	0.1	2	15	0.03~0.11
22	21.622.4	20.823.3	5	55	250	1	0.1	2	16	0.04~0.12
24	23.524.5	22.825.6	5	70	250	1	0.1	2	18	0.04~0.12
27	26.527.5	25.128.9	5	80	300	0.5	0.1	2	20	0.04~0.12
30	29.430.6	2832	5	80	300	0.5	0.1	2	22	0.04~0.12
33	32.333.7	3135	5	80	325	0.5	0.1	2	24	0.04~0.12
36	35.336.7	3438	5	90	350	0.5	0.1	2	27	0.04~0.12
39	38.239.8	3741	2.5	130	500	0.5	0.1	5	30	0.04~0.12
43	42.143.9	4046	2.5	150	500	0.5	0.1	5	33	0.04~0.12
47	46.147.9	4450	2.5	170	600	0.5	0.1	5	36	0.04~0.12
51	5052	4854	2.5	180	700	0.5	0.1	10	39	0.04~0.12
56	54.957.1	5260	2.5	200	700	0.5	0.1	10	43	0.04~0.12
62	60.863.2	5866	2.5	215	1000	0.5	0.1	10	47	0.04~0.12
68	66.669.4	6472	2.5	240	1000	0.5	0.1	10	51	0.04~0.12
75	73.576.5	7079	2.5	255	1000	0.5	0.1	10	51	0.04~0.12

**Notes:**2. Tested with pulses tp = 20 ms.





## TYPICAL CHARACTERISTICS CURVES

Fig 1: Typical Forward Current vs Forward Voltage

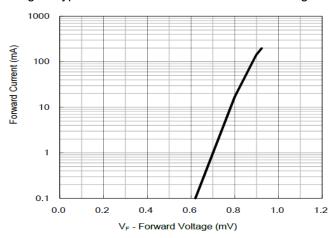


Fig 2: Dynamic Resistance vs Zener Current

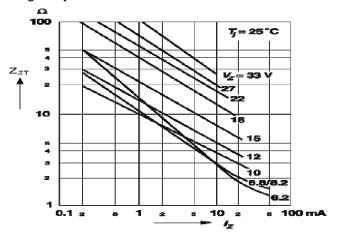


Fig. 3 Total Capacitance

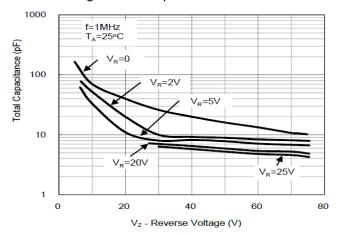


Fig 4: Dynamic Resistance vs Zener Current

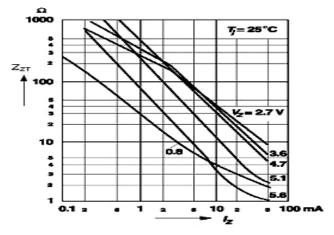
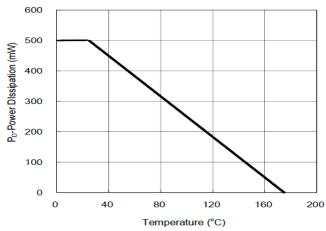


Fig. 5. Power Dissipation VS. Ambient Temperature

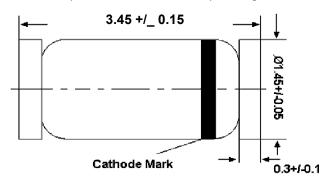






## **PACKAGE DETAILS**

# LL-34 (Glass Case Mini MELF)Package



All Dimension are in mm



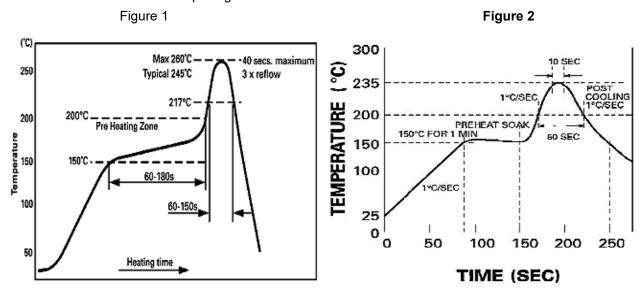


#### **Recommended Reflow Solder Profiles**

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.



#### Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System	
Average Ramp-Up Rate	~3°C/second	~3°C/second	
Preheat  - Temperature Range  - Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds	
Time maintained above:  – Temperature  – Time	200°C 30-50 seconds	217°C 60-150 seconds	
Peak Temperature	235°C	260°C max.	
Time within +0 -5°C of actual Peak	10 seconds	40 seconds	
Ramp-Down Rate	3°C/second max.	6°C/second max.	

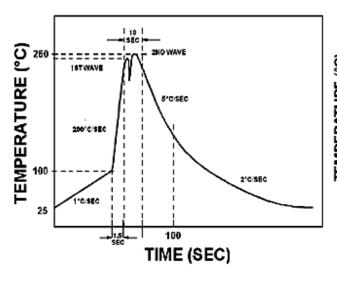


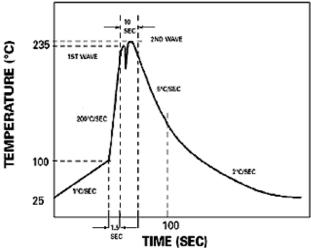


#### **Recommended Wave Solder Profiles**

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





#### **Wave Profiles in Tabular Form**

Profile Feature Sn-Pb System		Pb-Free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max





# Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

#### **Shelf Life of CDIL Products**

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

#### Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		

BZV55CXXX BZV55BXX $\overline{X}$  Rev03\_02032024GL/WW





#### **Customer Notes**

#### **Component Disposal Instructions**

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

#### **Disclaimer**

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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